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| 1. Record Nr.           | UNISALENTO991000358779707536  |
| Autore                  | Labiche, Eugene   |
| Titolo                  | Theatre / Labiche   |
| Pubbl/distr/stampa      | Paris : Gerard  |
| Descrizione fisica      | 374 p. ; 18 cm.   |
| Lingua di pubblicazione | Francese  |
| Formato                 | Materiale a stampa  |
| Livello bibliografico   | Monografia  |
| 2. Record Nr.           | UNINA9910787022703321   |
| Titolo                  | 11th international congress molded interconnect devices : scientific proceedings : selected, peer reviewed papers from the 11th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany // edited by Jorg Franke [and three others] |
| Pubbl/distr/stampa      | Pfaffikon, Switzerland : , : TTP, , 2014<br>Enfield, New Hampshire : , : Trans Tech Publications Ltd, , [date of distribution not identified]<br>©2014  |
| ISBN                    | 3-03826-636-1   |
| Descrizione fisica      | 1 online resource (119 p.)  |
| Collana                 | Advanced Materials Research, , 1662-8985 ; ; Volume 1038  |
| Disciplina              | 621.367   |
| Soggetti                | Molded interconnect devices<br>Three-dimensional display systems  |
| Lingua di pubblicazione | Inglese   |
| Formato                 | Materiale a stampa  |
| Livello bibliografico   | Monografia  |
| Note generali           | Description based upon print version of record.   |
| Nota di bibliografia    | Includes bibliographical references at the end of each chapters and index.  |
| Nota di contenuto       | 11th International Congress Molded Interconnect Devices - Scientific Proceedings; Preface and Committees; Table of Contents; Chapter 1:   |

Development and Prototyping; Method for the Identification and Comparison of Alternative Process Chains Focusing on Economics Efficiency Analysis during the Conceptual Design of Mechatronic Integrated Devices; Novel Approach for the Implementation of 3D-MID Compatible Routing Functionalities into Computer-Aided Design Tools; Optimized Process Sequences for Prototyping of Molded Interconnect Devices; Integration of Functional Circuits into FDM Parts  
Chapter 2: Printing Technologies  
Printing of Functional Structures on Molded 3D Devices; Electrical Functionalization of Thermoplastics by Combining Plasmadust Coating and Aerosol Jet Printing; Production of Miniaturized Sensor Structures on Polymer Substrates Using Inkjet Printing; Progress in the Manufacturing of Molded Interconnected Devices by 3D Microcontact Printing; Chapter 3: Materials and Manufacturing; Characterization of Electromagnetic Properties of MID Materials for High Frequency Applications up to 67 GHz  
Novel Laser Induced Metallization for Three Dimensional Molded Interconnect Device Applications by Spray Method  
Experimental Investigation of Laser Sintering of Conductive Adhesive for Functional Prototypes Produced by Embedding Stereolithography; MID Fabricated by Ultrasonic Processing; Usage of Industrial Robots as Flexible Handling Devices Supporting the Process of Three Dimensional Conductive Pattern Generation; Chapter 4: Manufacturing Processes; Study of MID Technologies for Automotive Lighting and Light Signaling Devices; Chapter 5: Assembly Technologies and Inspection  
Design and Solder Process Optimization in MID Technology for High Power Applications  
Chapter 6: Quality and Reliability; Hot Pin Pull Method - New Test Procedure for the Adhesion Measurement for 3D-MID; Keywords Index; Authors Index

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Sommario/riassunto

Collection of selected, peer reviewed papers from the 11 th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany. The 16 papers are grouped as follows: Chapter 1: Development and Prototyping, Chapter 2: Printing Technologies, Chapter 3: Materials and Manufacturing, Chapter 4: Manufacturing Processes, Chapter 5: Assembly Technologies and Inspection, Chapter 6: Quality and Reliability.

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